

A
BACHELOR'S DEGREE IN TELECOMMUNICATION ENGINEERING

Bachelor's Thesis

ACADEMIC COURSE 2021/2022

Tree Inspection Kit handheld device

AUTHOR:

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SUPERVISED BY:

Sr. Andrés Roldán Aranda

DEPARTMENT:

Electronics and Computer Technology



UNIVERSIDAD
DE GRANADA



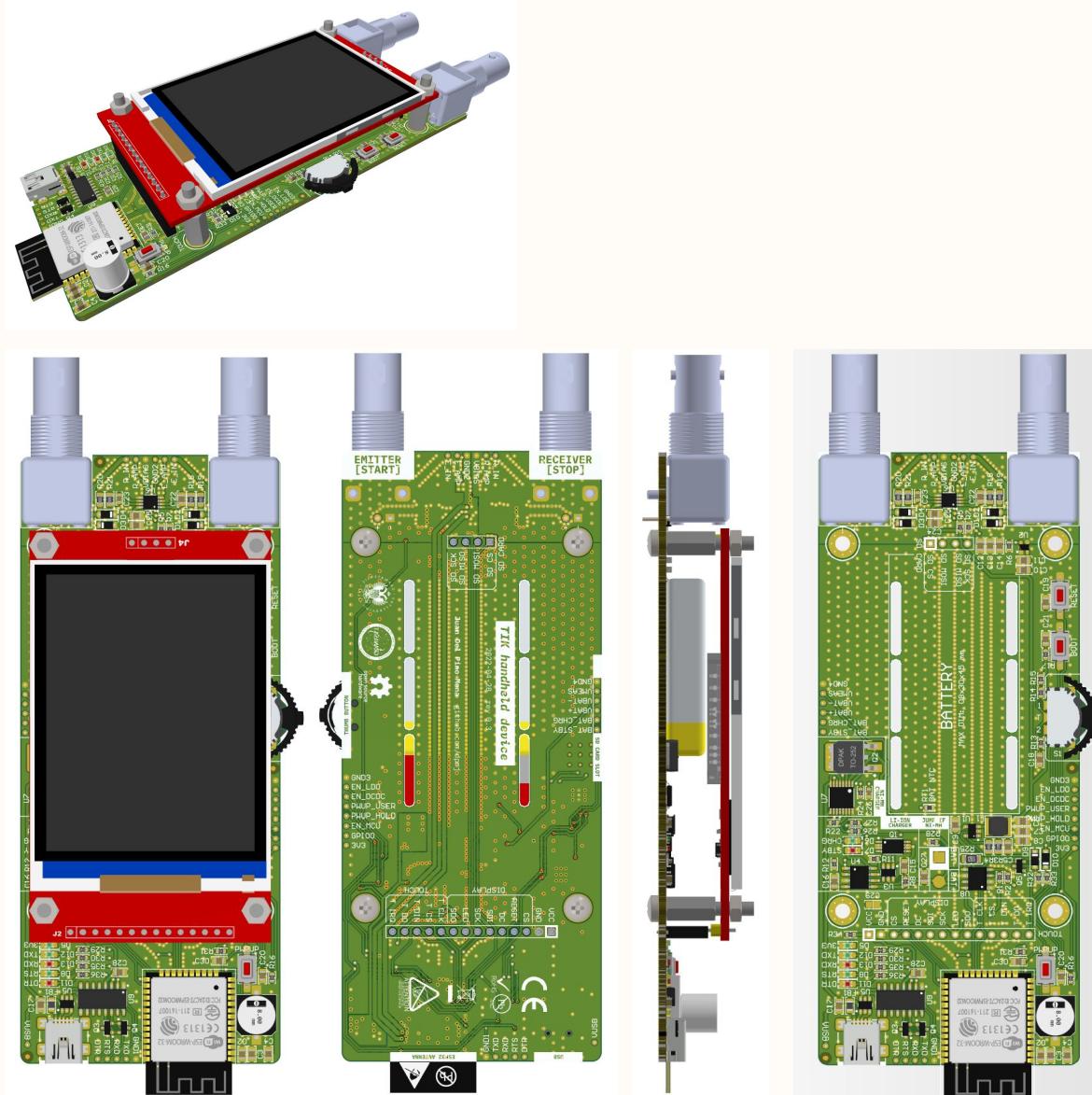
Project title: **TIK_HandheldDevice.PjPcb**

Date: **2022-05-04** Revision: **0.3**

Sheet 1 of 18

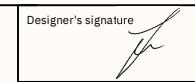
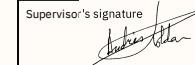
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Tree Inspection Kit handheld device

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Designer's signature

Supervisor's signature


Sheet title: **Introduction and PCB renders**
Project title: **TIK_HandheldDevice.PxjPcb**

Designer: **Juan Del Pino Mena**

Date: **2022-05-04** Revision: **0.3**

Sheet 2 of 18

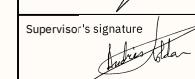
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Granada, Granada, Spain



A	<p># Revision 0.4 2022-05-10 [MOST RECENT]</p> <table border="1"> <thead> <tr> <th>NEW</th><th>FIXED</th></tr> </thead> <tbody> <tr> <td>- Added fabrication groups and fabrication order parameters.</td><td>- Corrected SPI and I2C pins on the ESP32.</td></tr> </tbody> </table>	NEW	FIXED	- Added fabrication groups and fabrication order parameters.	- Corrected SPI and I2C pins on the ESP32.	<p># Revision 0.2 2022-04-23</p> <table border="1"> <thead> <tr> <th>NEW</th><th>FIXED</th></tr> </thead> <tbody> <tr> <td>- New schematic hierarchy and system's block diagram. - Initial PCB layout</td><td>- Removed errors in the lithium charger - Removed errors in the adequation circuit - Changed ESD USB Protection IC. - Changed some adequation circuit values and made topology more clear. - Revised all passive components values and sizes to match existing component disponibility. - Corrected various pin definitions from the ESP32-WROOM-32D symbol</td></tr> </tbody> </table>	NEW	FIXED	- New schematic hierarchy and system's block diagram. - Initial PCB layout	- Removed errors in the lithium charger - Removed errors in the adequation circuit - Changed ESD USB Protection IC. - Changed some adequation circuit values and made topology more clear. - Revised all passive components values and sizes to match existing component disponibility. - Corrected various pin definitions from the ESP32-WROOM-32D symbol	B
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- TFT LCD / SD card connections. - First adequation circuit iteration - LiPo battery charger with TP4056 - Auto programming circuit.											

Revision history

Designer's signature

Supervisor's signature


Sheet title: **Changelog**
Project title: **TIK_HandheldDevice.PjPcb**
Designer: **Juan Del Pino Mena**
Date: **2022-05-04** Revision: **0.3**

Supervisor:
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Dpto. Electrónica y Tecnología de Computadores
University of Granada
C/Fuente Nueva, s/n, 18001
Granada, Granada, Spain



Maximum SPI traces length

Wavelength Calculator

Input Method	Wavelength Information
<input type="radio"/> Period	<input type="radio"/> Er Effective Information
<input checked="" type="radio"/> Frequency	<input type="radio"/> Speed of Light

Frequency: **80 MHz** Units: MHz kHz Hz

Er Eff: **2,8905**

Er Eff Calculator

$\lambda = \frac{C}{f * \sqrt{(ErEff)}}$

Note: Enter an Er Eff of 1 for wavelength in air.

Wavelength Divide: **1/20**

1/20 Wave Length: **11.02083 cm**

Bandwidth & Max Conductor Length

Input Method	Speed of Light
<input type="radio"/> Signal Risetime	<input type="radio"/> Frequency
<input checked="" type="radio"/> Frequency	<input type="radio"/> Units

f Units: MHz kHz Hz

Frequency: **80 MHz**

Frequency Domain Method

Full Wavelength (In Air): **374.74057 cm**

Lambda Divide by Factor: **1/20**

Maximum Conductor Length: **18.73703 cm**

Maximum Analog traces length

Wavelength Calculator

Input Method	Wavelength Information
<input type="radio"/> Period	<input type="radio"/> Er Effective Information
<input checked="" type="radio"/> Frequency	<input type="radio"/> Speed of Light

Frequency: **100 KHz** Units: MHz kHz Hz

Er Eff: **3,0832**

Er Eff Calculator

$\lambda = \frac{C}{f * \sqrt{(ErEff)}}$

Note: Enter an Er Eff of 1 for wavelength in air.

Wavelength Divide: **1/20**

1/20 Wave Length: **8536.69684 cm**

Analog signal trace impedance

Conductor Impedance

Conductor Width (W)	Formula Restrictions:
0,8 mm	$0.1 < W/H < 2.0$
Conductor Height (H)	$T = 53\mu m$
1,5 mm	<input type="checkbox"/> Help
Conductor Gap (G)	0,254 mm

W/H = 0.533

Z₀: **60.6257 Ohms**

Power traces conductor characteristics (DC)

0.5 mm wide traces

Conductor Characteristics

Solve For	<input type="radio"/> Amperage	<input type="radio"/> No																	
Plane Present?	<input type="radio"/> No	<input checked="" type="radio"/> Yes																	
Conductor Width	0,5 mm	Conductor Length	1 mm																
PCB Thickness	1,6 mm	Frequency	<input checked="" type="checkbox"/> DC																
Distance to Plane	1,5 mm	Plating Thickness	<input type="radio"/> Bare PCB <input type="radio"/> 18um <input type="radio"/> 35um <input type="radio"/> 53um <input type="radio"/> 70um <input type="radio"/> 88um <input type="radio"/> 106um <input type="radio"/> 124um <input type="radio"/> 142um <input type="radio"/> 178um																
Power Dissipation	0.00397 Watts	Units	<input type="radio"/> Imperial <input checked="" type="radio"/> Metric																
Conductor DC Resistance	0.00065 Ohms	Substrate Options	FR-4 STD																
Power Dissipation in dBm	5.9921 dBm	Conductor Cross Section	0.0301 Sq.mm	Voltage Drop	0.0016 Volts	Parallel Conductors?	<input type="radio"/> No <input checked="" type="radio"/> Yes	Conductor Current	2.4647 Amps	Material Selection	FR-4 STD	Information	Total Copper Thickness 70 um	Temp Rise (°C)	4,6		Via Thermal Resistance N/A	ER Tg (°C)	130
Conductor Cross Section	0.0301 Sq.mm																		
Voltage Drop	0.0016 Volts	Parallel Conductors?	<input type="radio"/> No <input checked="" type="radio"/> Yes																
Conductor Current	2.4647 Amps	Material Selection	FR-4 STD																
Information	Total Copper Thickness 70 um	Temp Rise (°C)	4,6																
	Via Thermal Resistance N/A	ER Tg (°C)	130																

IPC-2152 with modifiers mode Etch Factor: 1:1

Power Dissipation: **0.00397 Watts** Conductor DC Resistance: **0.00065 Ohms**

Power Dissipation in dBm: **5.9921 dBm** Conductor Cross Section: **0.0301 Sq.mm**

Voltage Drop: **0.0016 Volts** Conductor Current: **2.4647 Amps**

Information: Total Copper Thickness 70 um Via Thermal Resistance N/A

0.35 mm wide traces

Conductor Characteristics

Solve For	<input type="radio"/> Amperage	<input type="radio"/> No																	
Plane Present?	<input type="radio"/> No	<input checked="" type="radio"/> Yes																	
Conductor Width	0,35 mm	Conductor Length	1 mm																
PCB Thickness	1,6 mm	Frequency	<input checked="" type="checkbox"/> DC																
Distance to Plane	1,5 mm	Plating Thickness	<input type="radio"/> Bare PCB <input type="radio"/> 18um <input type="radio"/> 35um <input type="radio"/> 53um <input type="radio"/> 70um <input type="radio"/> 88um <input type="radio"/> 106um <input type="radio"/> 124um <input type="radio"/> 178um																
Power Dissipation	0.00371 Watts	Units	<input type="radio"/> Imperial <input checked="" type="radio"/> Metric																
Conductor DC Resistance	0.00100 Ohms	Substrate Options	FR-4 STD																
Power Dissipation in dBm	5.6940 dBm	Conductor Cross Section	0.0196 Sq.mm	Voltage Drop	0.0019 Volts	Parallel Conductors?	<input type="radio"/> No <input checked="" type="radio"/> Yes	Conductor Current	1.9218 Amps	Material Selection	FR-4 STD	Information	Total Copper Thickness 70 um	Temp Rise (°C)	4,6		Via Thermal Resistance N/A	ER Tg (°C)	130
Conductor Cross Section	0.0196 Sq.mm																		
Voltage Drop	0.0019 Volts	Parallel Conductors?	<input type="radio"/> No <input checked="" type="radio"/> Yes																
Conductor Current	1.9218 Amps	Material Selection	FR-4 STD																
Information	Total Copper Thickness 70 um	Temp Rise (°C)	4,6																
	Via Thermal Resistance N/A	ER Tg (°C)	130																

IPC-2152 with modifiers mode Etch Factor: 1:1

Power Dissipation: **0.00371 Watts** Conductor DC Resistance: **0.00100 Ohms**

Power Dissipation in dBm: **5.6940 dBm** Conductor Cross Section: **0.0196 Sq.mm**

Voltage Drop: **0.0019 Volts** Conductor Current: **1.9218 Amps**

Information: Total Copper Thickness 70 um Via Thermal Resistance N/A

Via characteristics

Via Characteristics

Via Hole Diameter	0,3 mm
Internal Pad Diameter	0,6 mm
Ref Plane Opening Diam	1,016 mm
Via Height	1,6 mm
Via Plating Thickness	0,035 mm

IPC-2152 with modifiers mode

Via Capacitance	Via DC Resistance	Power Dissipation
0.5893 pF	0.00086 Ohms	0.00326 Watts
Via Inductance	Resonant Frequency	Conductor Cross Section
1.2993 nH	5751.849 MHz	0.0368 Sq.mm
Via Impedance	Step Response	Via Current
46.956 Ohms	30.4373 ps	1.9514 Amps

Trace & via characteristics

Trace width based on results from PCB Toolkit by Saturn PCB Design INC.

*

**TO-DO: EXPLAIN DATA.
CROP SOME
SCREENSHOTS**

Designer's signature

Sheet title: **Trace width design**

Project title: **TIK_HandheldDevice.PjPcb**

Supervisor's signature

Desinger: **Juan Del Pino Mena**

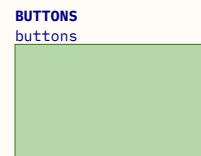
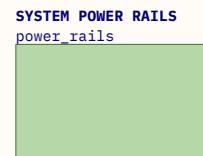
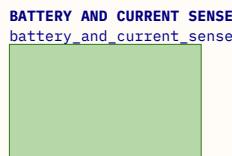
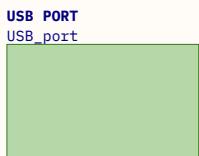
Date: **2022-05-04** Revision: **0.3**

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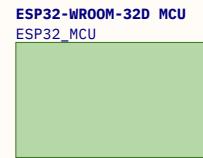
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A



B

B



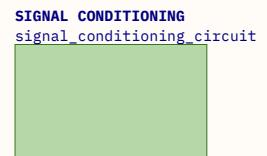
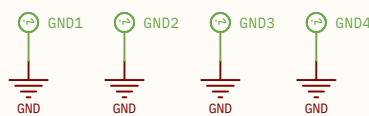
C

C

Fiducials



GND test points



Block diagram

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TO-DO: ARROWS
INDICATING WHERE
SIGNALS GO

Designer's signature

Sheet title: **Block diagram**

Project title: **TIK_HandheldDevice.PrjPcb**

Supervisor's signature

Designer: **Juan Del Pino Mena**

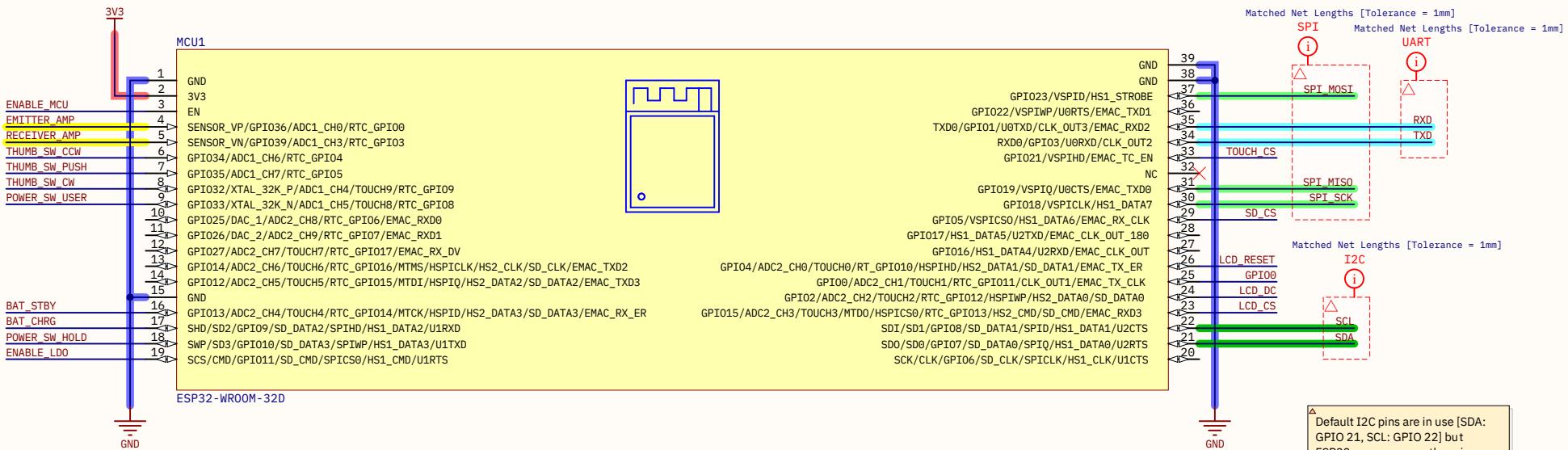
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Sheet 5 of 18

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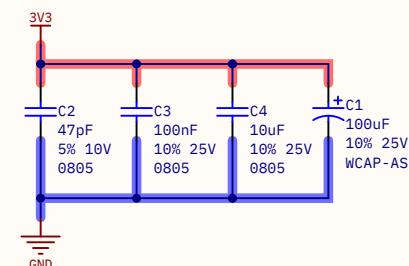
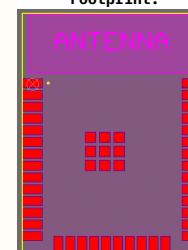


A



ADC2 pins are not usable while using Wi-Fi or Bluetooth and should be left unused if not necessary

GPIO34, GPIO35, GPIO36 & GPIO39 are input-only



Recommended smoothing/bypass capacitors are 0.1 μ F and 10 μ F, ceramic, low ESR. Should be placed close to the chip and with short return paths. [ESP32-WROOM-32D datasheet, page 21]

Added one extra 100 μ F electrolytic cap to filter current spikes during ESP32 RF usage and a small 47pF capacitor to be more effective on high frequencies

ESP32-WROOM-32D MCU, Wi-Fi + Bluetooth module

MCU hardware configuration and I/O pins

*

Designer's signature Supervisor: Sr. Andrés Roldán Aranda
Project title: TIK_HandheldDevice.PjPcb
Supervisor's signature Desighner: Juan Del Pino Mena
Date: 2022-05-04 Revision: 0.3 Sheet 6 of 18

Sheet title: ESP32-WROOM-32D MCU

Project title: TIK_HandheldDevice.PjPcb

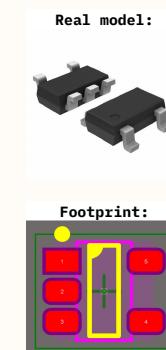
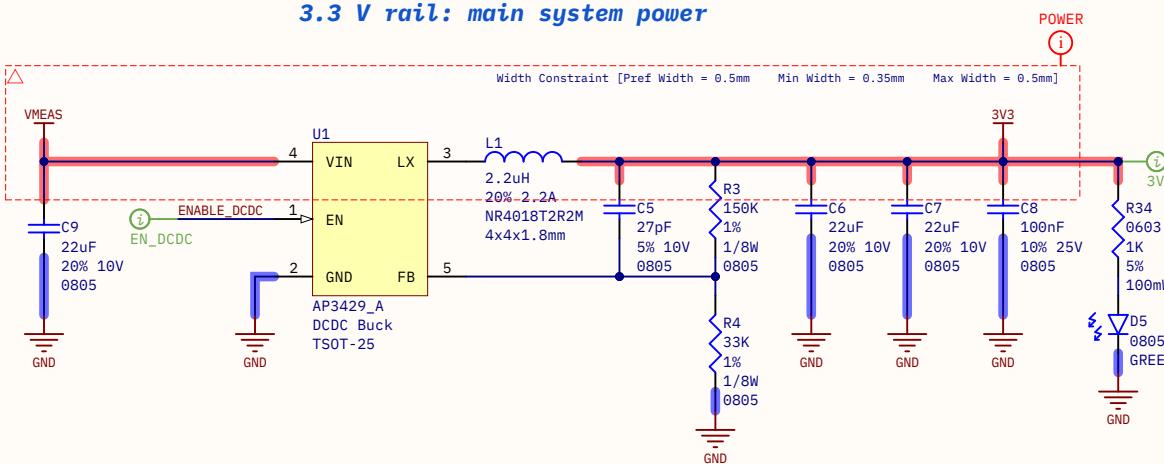
Desighner: Juan Del Pino Mena

Date: 2022-05-04 Revision: 0.3 Sheet 6 of 18

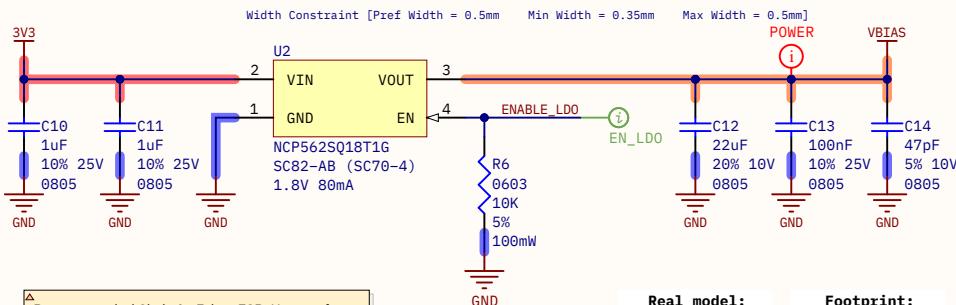


Typical Application Circuit. [AP3429/A datasheet, page 2] with some values modified as needed and/or part availability. Capacitors should be placed close to the chip and circuit should be traced in short loops. Feedback voltage V_{FB} is 0.6 V const.

Resistors are adjusted as a voltage divider. So, if 3.3V are needed at the converter output: $V_{FB} = 0.6V = V_{out} \cdot (R2)/(R1+R2) \rightarrow R2 = 2/9 \cdot R1$. Resistor values must be high (kOhms) in order to maintain a low power consumption on the feedback circuit.

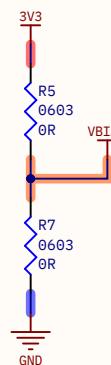


1.8 V rail: Vbias for signal conditioning circuit



Recommended C_{in} is 1 uF, low ESR. Usage of multiple input capacitors to reduce ESR and ESL. There are no recommended values for C_{out} but these caps should probe more than enough to have low ESR and reduce ripple at a wide frequency range. Datasheet specifies a typical 100 uVRms noise on V_{out} , somewhat high.

Optional 1V8 rail bypass jumpers



IMPORTANT: 1V8 rail is bypassable by soldering these optional 0-0H resistors. This is for experimenting with different voltages and if it affects the overall performance of the acquisition circuit.

Do NOT connect both OR resistors at the same time or it will jump VCC and GND. And keep the LDO disabled at all times.

This can also be used to insert a voltage divider. i.e.: if you want to reduce the rail voltage to VCC/2 you only have to add two ≥ 10 KOhm 0603 resistors. Just keep in mind that voltage won't be as stable as in a LDO as it will be greatly dependent on the load impedance.

If you do this, populate the LDO's output caps, so VBIAS it behaves as a small-signal GND.

Power rails

Battery DC/DC step-down converter and Vbias for signal conditioning circuit.

Designer's signature
Supervisor's signature

Sheet title: *
Project title: TIK_HandheldDevice.PjPcb

Designer: Juan Del Pino Mena

Date: 2022-05-04 Revision: 0.3 Sheet 7 of 18

Supervisor:
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Battery charging circuit variants

BATTERY CHARGER [VARIANT #1: NiMH]
battery_charger_ni_mh

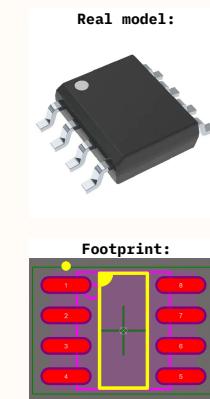
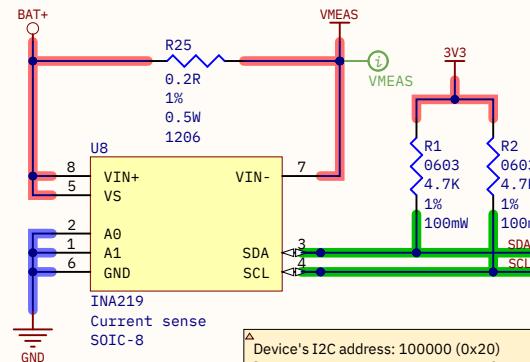


BATTERY CHARGER [VARIANT #2: LI-ION]
battery_charger_li-ion



Two circuit variants are implemented BUT NOT USED SIMULTANEOUSLY. Only one must be populated at a time.
The usage of one over the other will come by component disponibility.

Battery output current sense and voltage monitor



Battery connector. Charger selection jumper. Battery thermistor

Width Constraint [Pref Width = 0.5mm Min Width = 0.35mm Max Width = 0.5mm] POWER

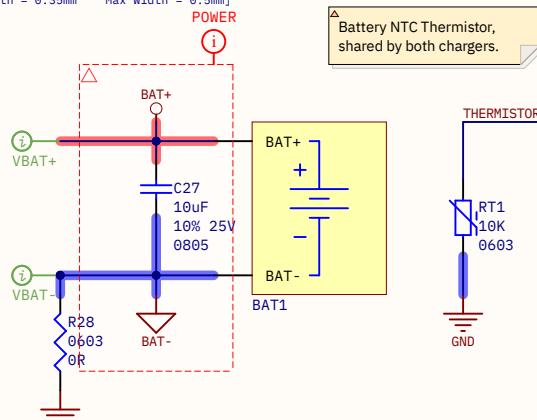
IMPORTANT: 0-Ohm jumper for charger selection:

The battery share the connector between the 2 possible chargers.

However, on the Lithium one BAT- is not connected to the system GND for protection; but in the case of the NiMH one it is.

So, to avoid shorting BAT- and GND on the Li-Ion charger, DO NOT place the 0-ohm jumper.

On the other hand if you are using the NiMH charger solder you MUST use the jumper.

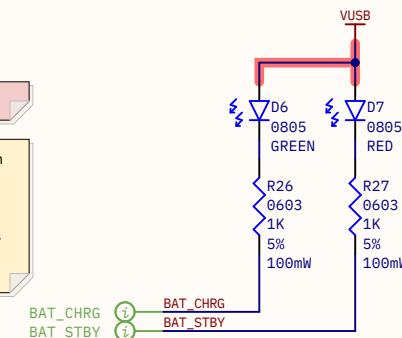


Charging status indicator

These signals come from both charging IC's.

They are status outputs that are normally on high impedance and they are pulled LOW when activated.

We can use these pins to turn on some LEDs and to notify the microcontroller of the charging status.



Battery and current sense

Two circuit variants that will be implemented but not used simultaneously. The usage of one over the other will come by component disponibility. INA219 current sensor is independent and common for both systems.

Designer's signature
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Sheet title: **Battery and current sense**

Project title: **TIK_HandheldDevice.PjPcb**

Designer: **Juan Del Pino Mena**

Date: **2022-05-04**

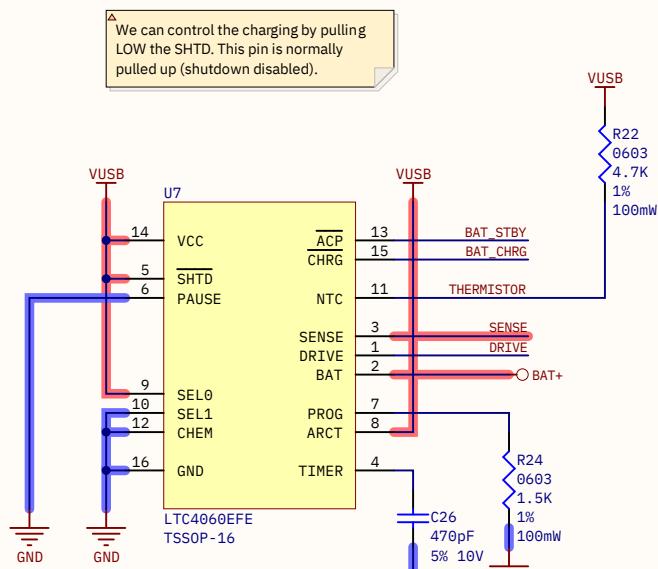
Revision: **0.3**

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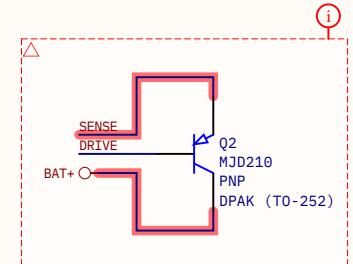


NiMH/NiCd battery charger IC



Width Constraint [Pref Width = 0.5mm Min Width = 0.35mm Max Width = 0.5mm]

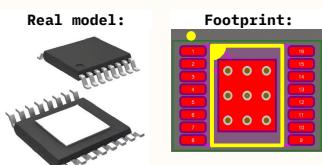
POWER



Following the [LTC4060 datasheet, page 13], if using a 10 K NTC thermistor, Its RHOT should be 4.42 k Ω , 1% to trigger the temperature warning at 45 °C. However, this value being too much specific is problematic.

This can be disabled by connecting a 0-ohm resistor in place of the thermistor.

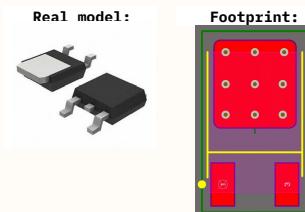
[NOT IMPLEMENTED] This IC has the possibility of implementing a power path control (power the load from external source while charging)



TIMER capacitor and PROG resistor program the charge Tmax (maximum charging time, a security measure). [LTC4060 datasheet, page 13]. These values should complete a full charge in at most 1 h 6'.

PROG resistor programs the maximum current that the battery will receive while charging. For 1.5 k Ω this is 0.93 A.

i.e.: a 1000 mAh battery will charge at approx 1C with this configuration, but can be insufficient time for a 3000 mAh one.



Battery charging circuitry for Ni-MH

Battery charger circuit variant #1. By default the device uses a Nickel-metal hydride battery which are chemically and thermally more stable (and safer) than Lithium-based ones; at the cost of a lower charge/volume ratio.

Designer's signature
Supervisor's signature

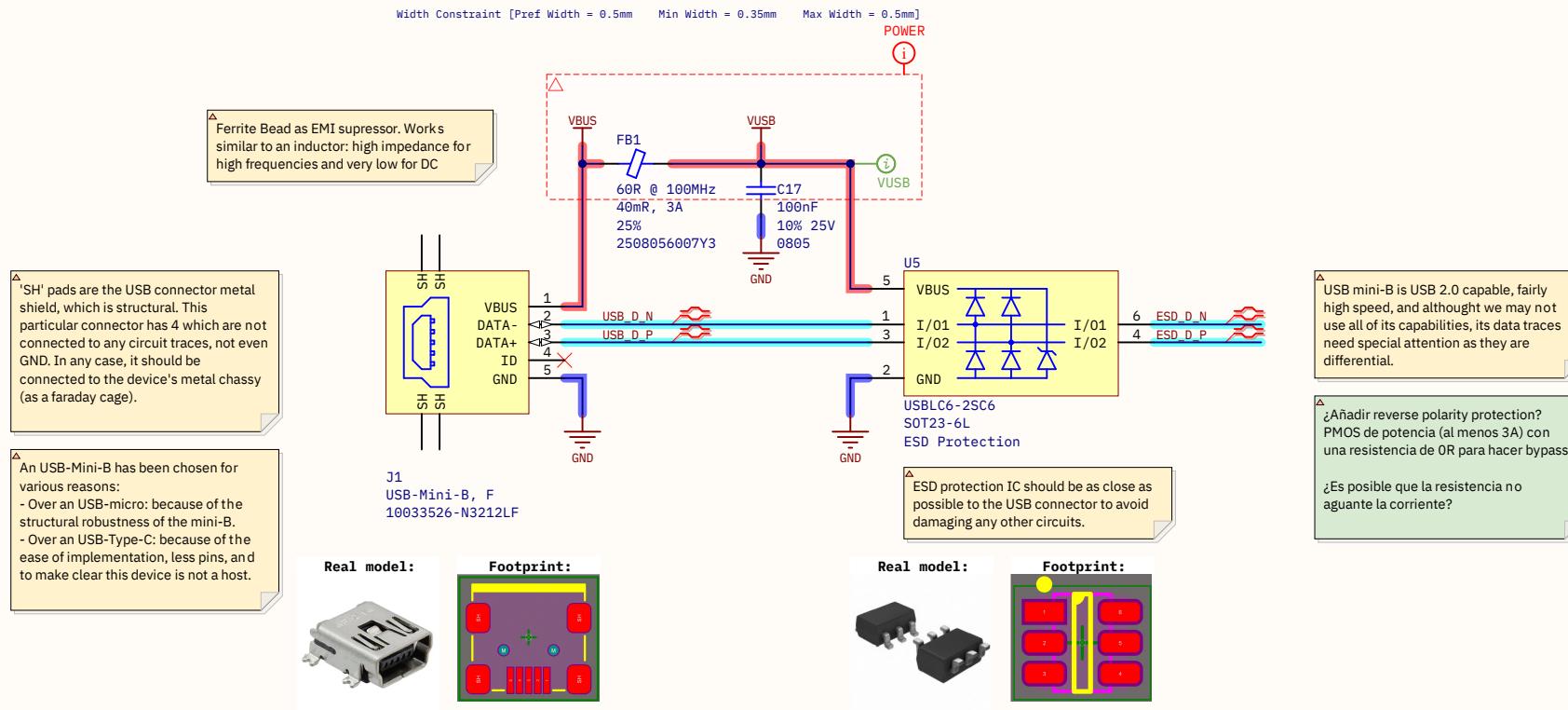
Sheet title: **Battery charger**
Project title: **TIK_HandheldDevice.PjPcb**

Desinger: **Juan Del Pino Mena**

Date: **2022-05-04** Revision: **0.3** Sheet 9 of 18

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USB connector and ESD protection circuit

USB is used as a programming interface, as well as a power source for the charging circuit. Since it's an external connector, it needs to have a protection circuit against electro-static discharge (ESD) and noise.

Designer's signature
Supervisor's signature

Sheet title: **USB connector and ESD protection circuit**

Project title: **TIK_HandheldDevice.PxjPcb**

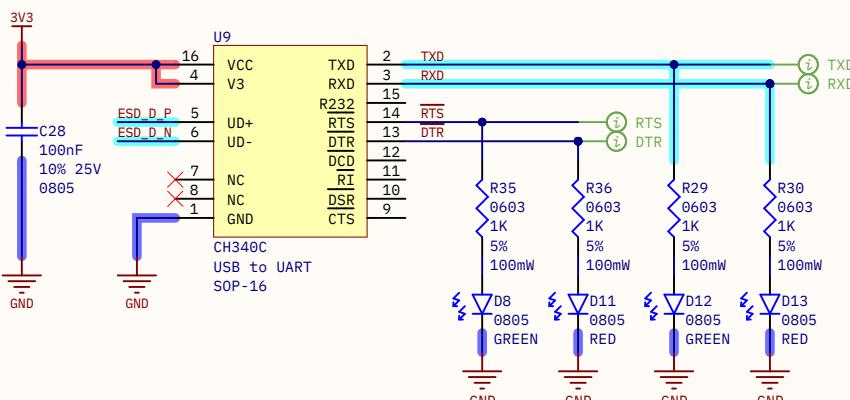
Designer: **Juan Del Pino Mena**

Date: **2022-05-04** Revision: **0.3** Sheet 11 of 18

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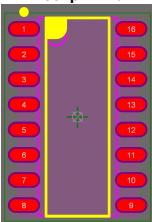
USB to UART conversion



Real model:

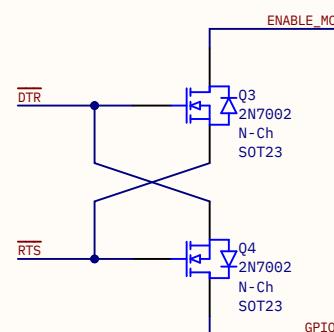


Footprint:



These LEDs serve as testimonies of
UART communication and help
during debugging process

Auto programming circuit



ESP32 GPIO0 is a Strapping pin. Strapping pins modify the device's boot mode during chip reset (enable pin pulled down)
GPIO0 is pulled up during reset. ESP_ENABLE is pulled up by an external pullup resistor

When GPIO0 is HIGH, it boots from internal SPI memory, but when it's LOW the boot sequence changes to 'Download' and we can upload a program to the MCU.

[ESP32 Datasheet, section 2.4, pages 19-20]

Circuit truth table

DTR	RTS	ENABLE_MCU	GPIO0
0	0	1	1
0	1	1	0
1	0	0	1
1	1	1	1

USB to UART and MCU programming

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Designer's signature
Supervisor's signature

Sheet title: **USB to UART and MCU programming**

Project title: **TIK_HandheldDevice.PrtPcb**

Designer: **Juan Del Pino Mena**

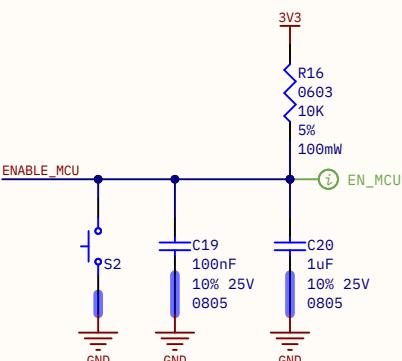
Date: **2022-05-04** Revision: **0.3**

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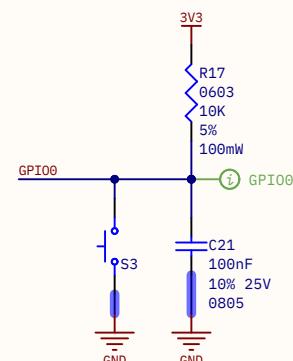


Reset

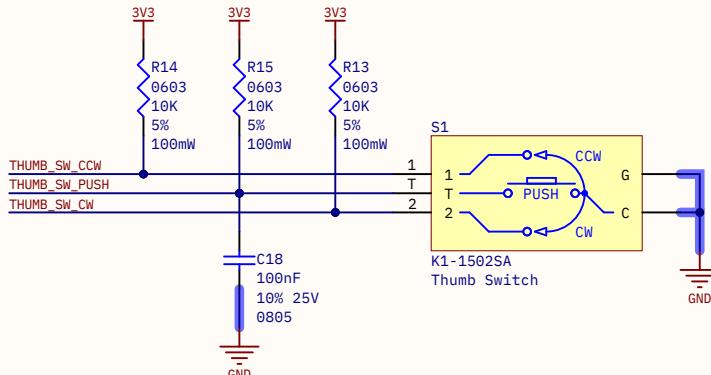
To ensure power stability to the microcontroller during powerup, this RC filter introduces a delay on the ENABLE pin. Usual values are $10\text{ k}\Omega$, $1\text{ }\mu\text{F}$ ($\tau = 10\text{ ms}$, $t_{\{10-90\}} = 22\text{ ms}$).
[ESP32-WROOM-32D datasheet, page 22]

**Boot mode selection (debug)**

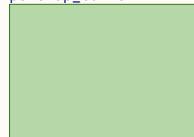
Allows to force 'Download' boot sequence
Same design as in ESP32 DevKit boards.
100 nF cap are for debouncing and should be placed close to the buttons

**Multidirection 'thumb' button (UI navigation)**

Horizontal SMD device, multi-directional / muti-function rotary slider button.
Accessed from the right side.



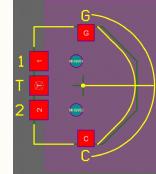
POWERUP BUTTON
powerup_button



Real model:



Footprint:

**Buttons**

TFT LCD touchscreen, rotary encoder, on/off and reset switches

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Supervisor's signature

Sheet title: **Buttons**
Project title: **TIK_HandheldDevice.PjPcb**

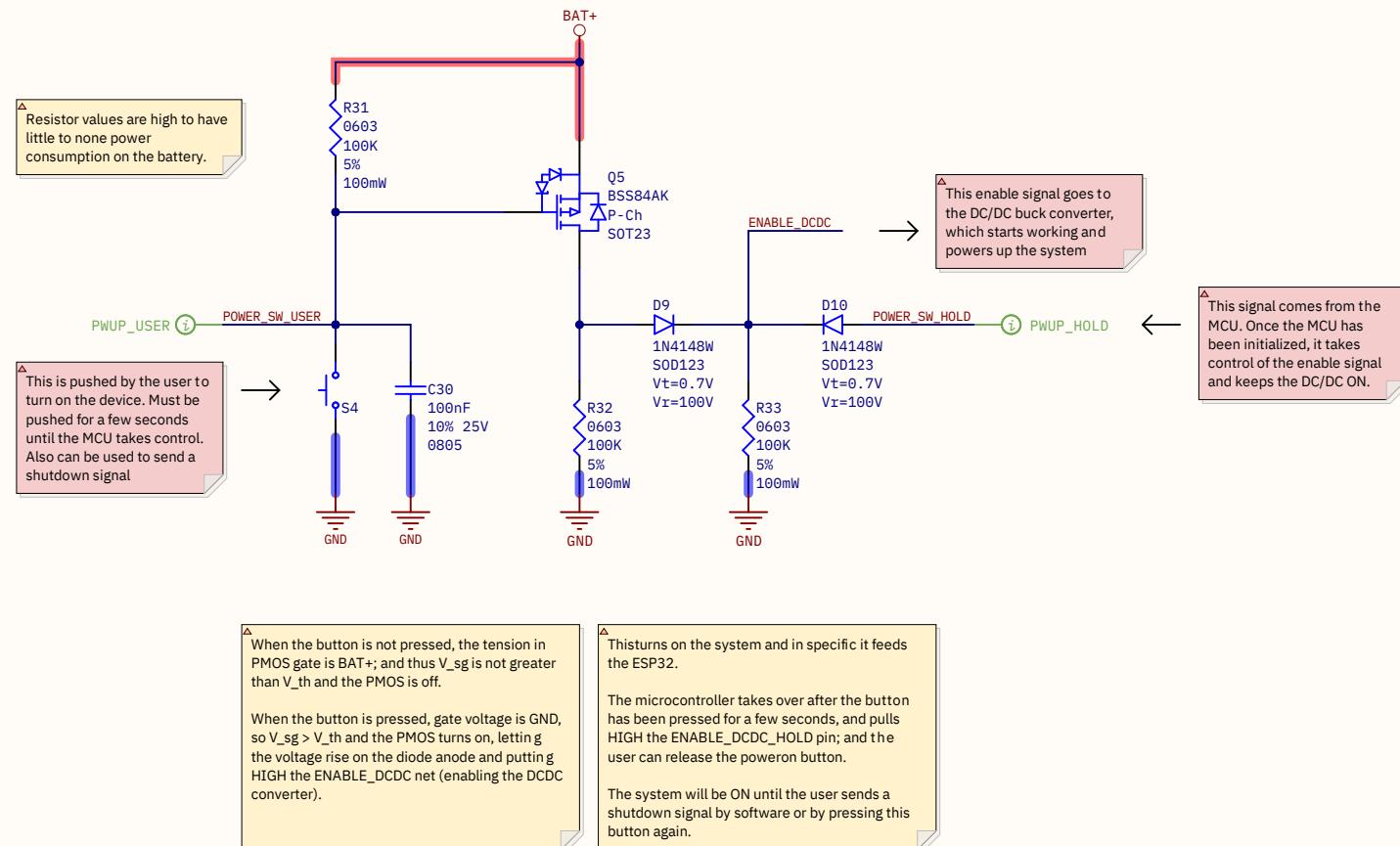
Designer: **Juan Del Pino Mena**

Date: **2022-05-04** Revision: **0.3** Sheet 13 of 18

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Powerup button

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Designer's signature
Supervisor's signature

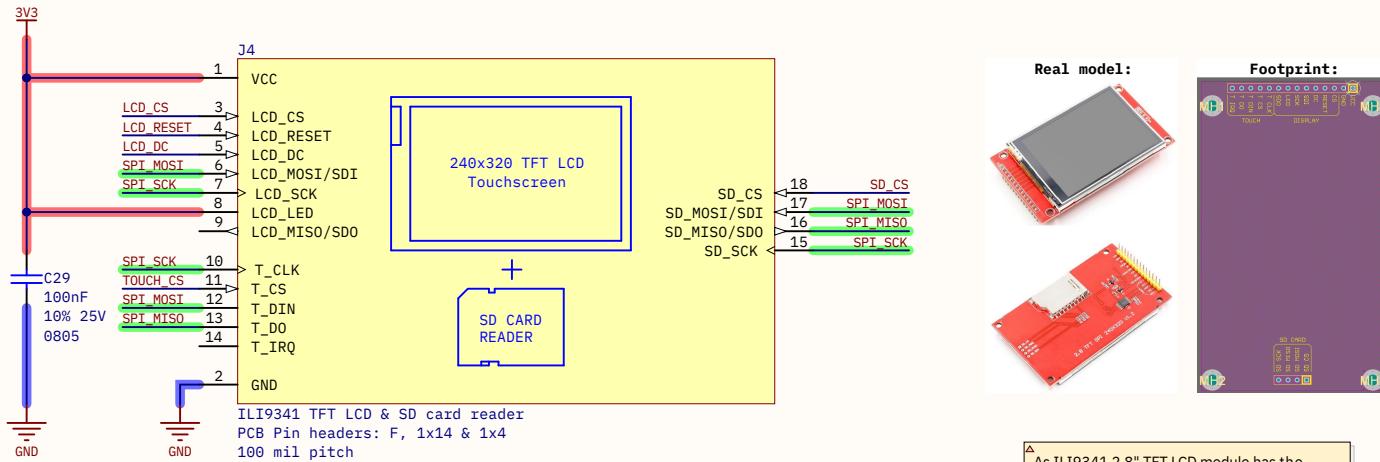
Sheet title: **Powerup button**
Project title: **TIK_HandheldDevice.PjPcb**

Designer: **Juan Del Pino Mena**

Date: **2022-05-04** Revision: **0.3** Sheet 14 of 18

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LCD TFT Touch Display & SD card reader

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Supervisor's signature

Sheet title: **LCD TFT Touch Display & SD card reader**

Project title: **TIK_HandheldDevice.PjPcb**

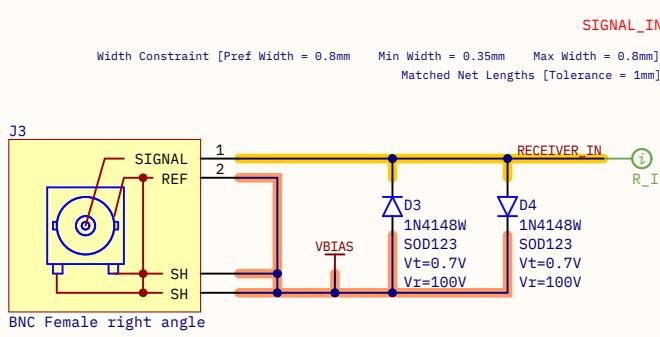
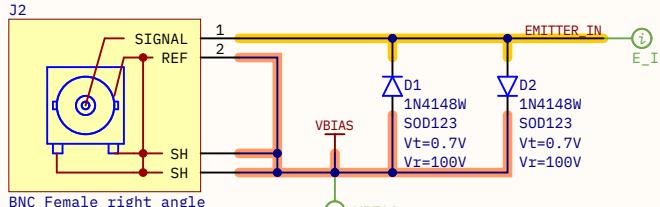
Designer: **Juan Del Pino Mena**

Date: **2022-05-04** Revision: **0.3** Sheet 15 of 18

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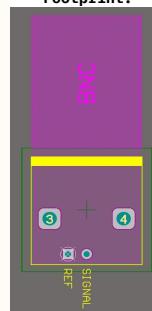
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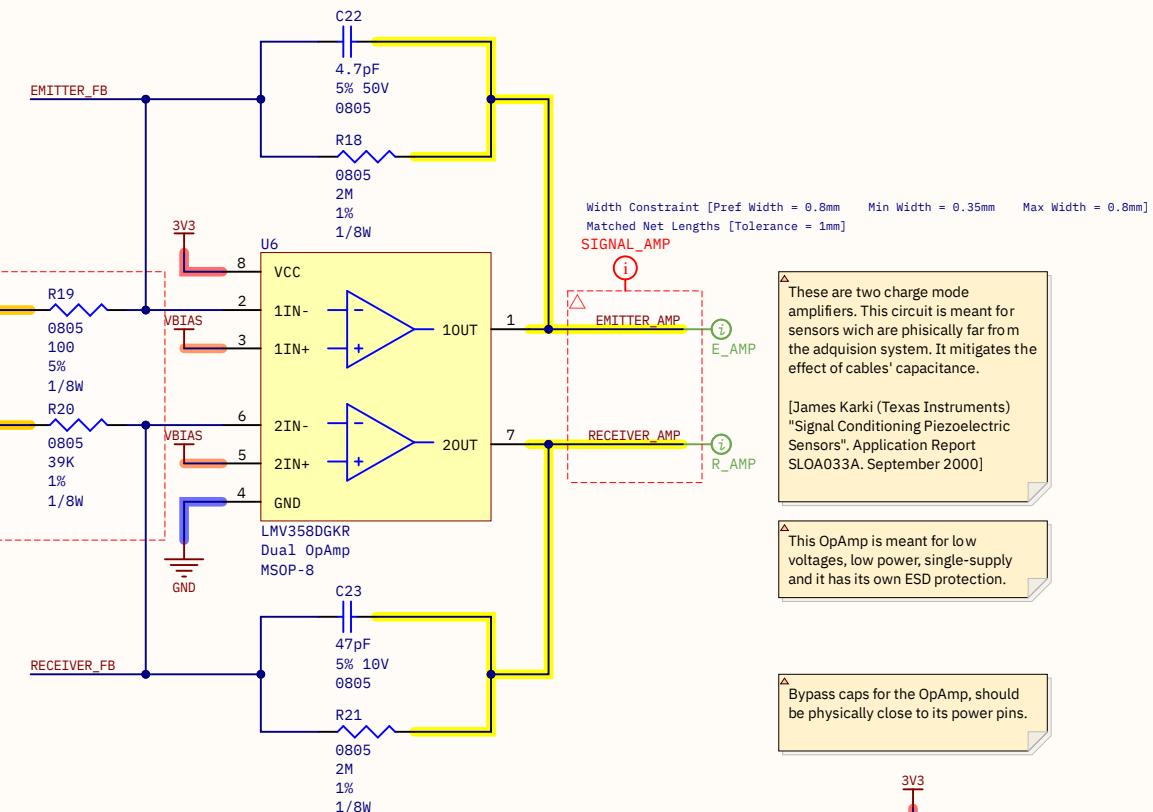
Real model:



Footprint:



Emitter signal will be in the range of 15 V to 100 V and need to be clipped. Then, the OpAmp will amplify it by perceived by the instrument as a flank; whereas receiver signal most likely will be amplified without any clipping.

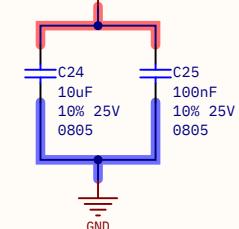


These are two charge mode amplifiers. This circuit is meant for sensors which are physically far from the acquisition system. It mitigates the effect of cables' capacitance.

[James Karki (Texas Instruments)
"Signal Conditioning Piezoelectric Sensors". Application Report
SLOA033A. September 2000]

This OpAmp is meant for low voltages, low power, single-supply and it has its own ESD protection.

Bypass caps for the OpAmp, should be physically close to its power pins.



Signal conditioning circuit

Signal comes from piezoelectric sensors and need to be converted from charge to voltage. Three sensors that have been used for this project proved to generate up to -100 volts peak, so it needs clipping

Designer's signature
Supervisor's signature

Sheet title: Signal conditioning circuit
Project title: TIK_HandheldDevice.PjPcb

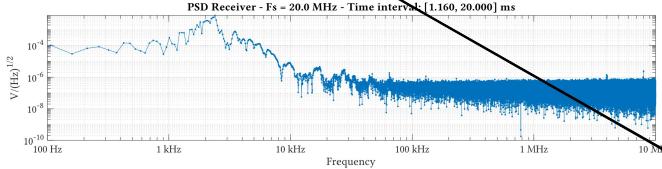
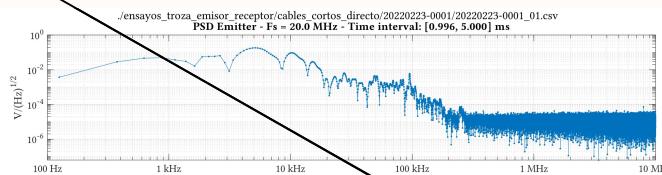
Designer: Juan Del Pino Mena

Date: 2022-05-04 Revision: 0.3 Sheet 16 of 18

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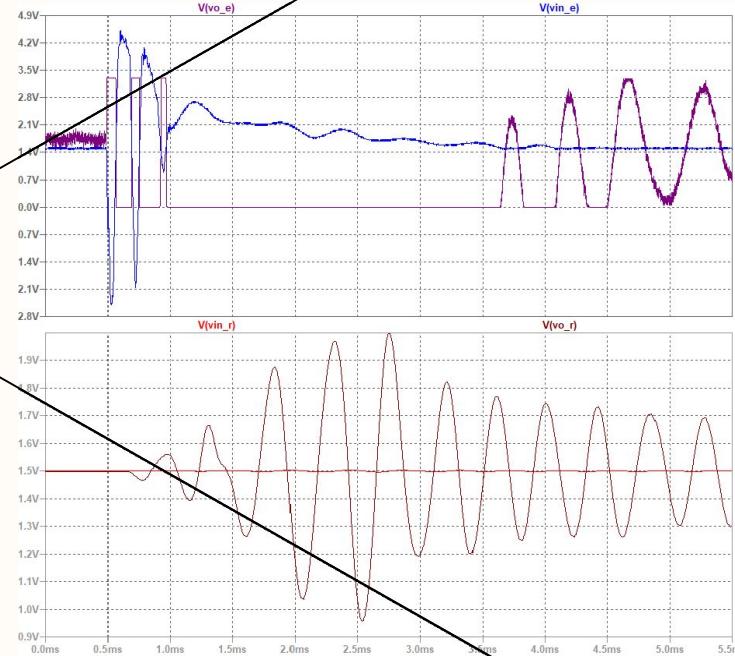


Example of a Voltage Spectral Density of trunk signals

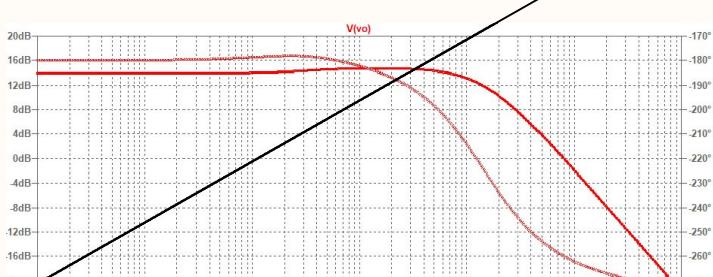
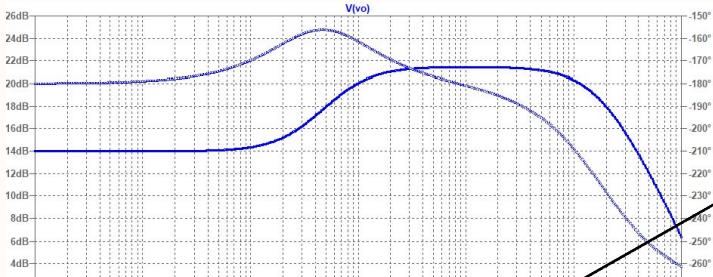


A REVISAR Y REPETIR EN ALTIUM

Time behavior



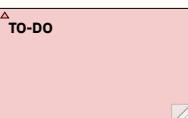
Conditioning circuit theoretical frequency response



Respuesta en frecuencia teórica, con el modelo UniversalOpAmp, cable con 700 pF y R del piezo 2 M Ω
¿Afecta en algo la fase?

Signal conditioning theoreticals

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Supervisor's signature

Sheet title: Signal Conditioning Theoreticals

Project title: TIK_HandheldDevice.PxjPcb

Designer: Juan Del Pino Mena

Date: 2022-05-04 Revision: 0.3 Sheet 17 of 18

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A

A

B

B

C

C

D

D

Power budget

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Designer's signature

Supervisor's signature

Sheet title: **Power budget**

Project title: **TIK_HandheldDevice.PxjPcb**

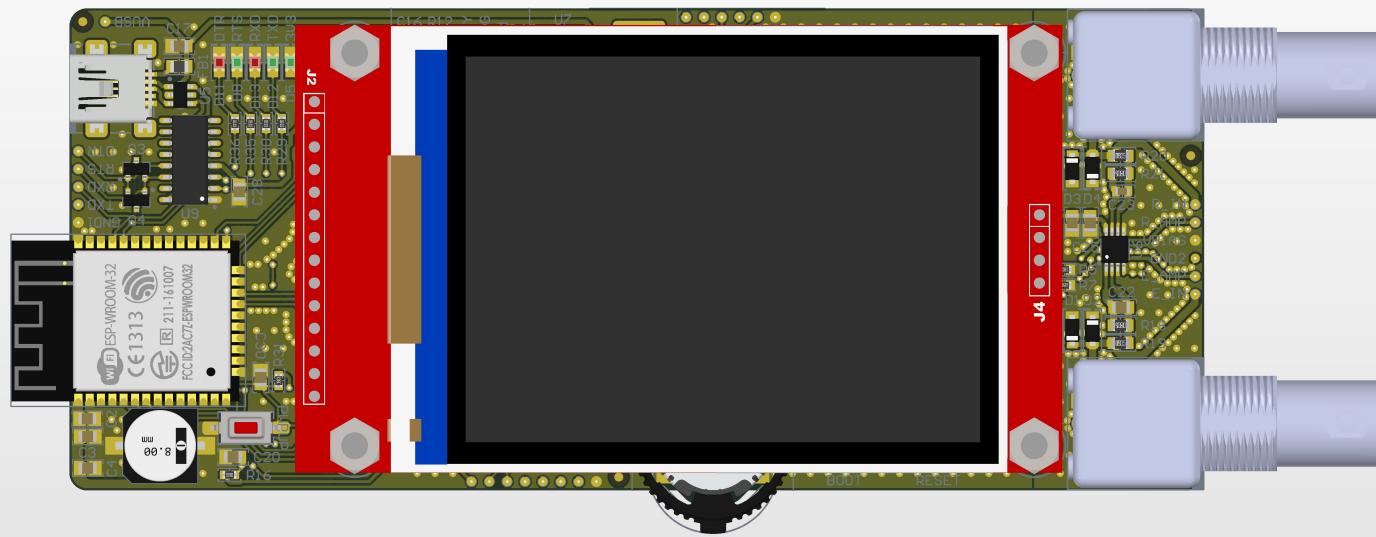
Designer: **Juan Del Pino Mena**

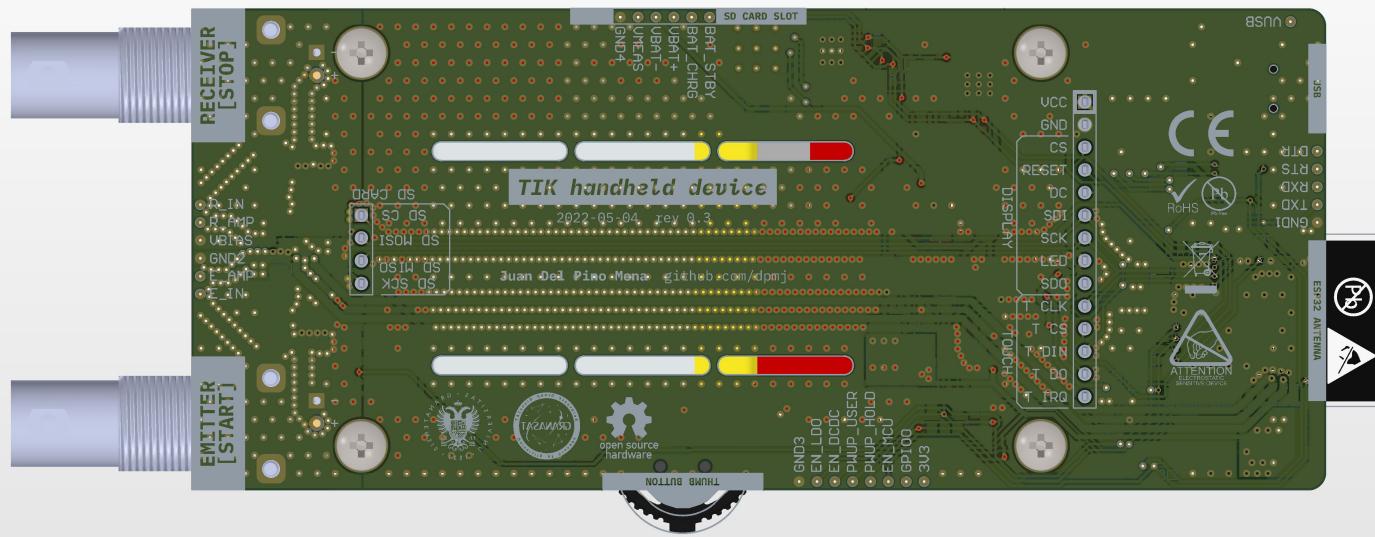
Date: **2022-05-04** Revision: **0.3**

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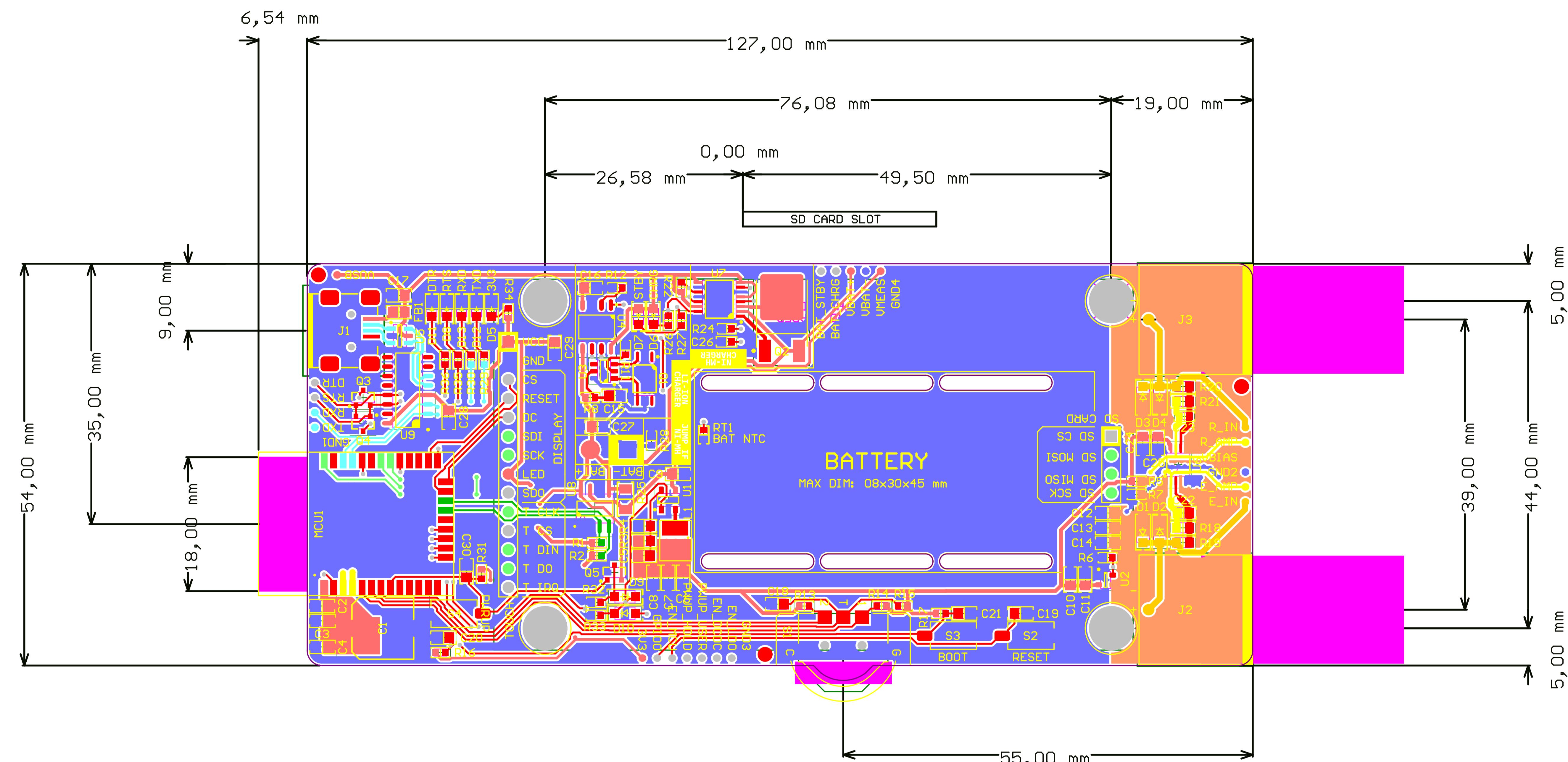
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A

**VISIBLE LAYERS:**

Board outline + Multilayer + Top
overlay + Mechanical 15 + Top
layer + Keep-out + dimensions

TIK handheld device PCB

PCB orientation: vertical. Screen facing front, BNCs on top, USB at the bottom, SD Card reader at the left, powerup button at the bottom front right, and multipurpose button on the right side.

Designer's signature:

Sheet title: TIK Handheld Device PCB

Project title: TIK_HandheldDevice

Supervisor's signature:

Designer: Juan Del Pino Mena

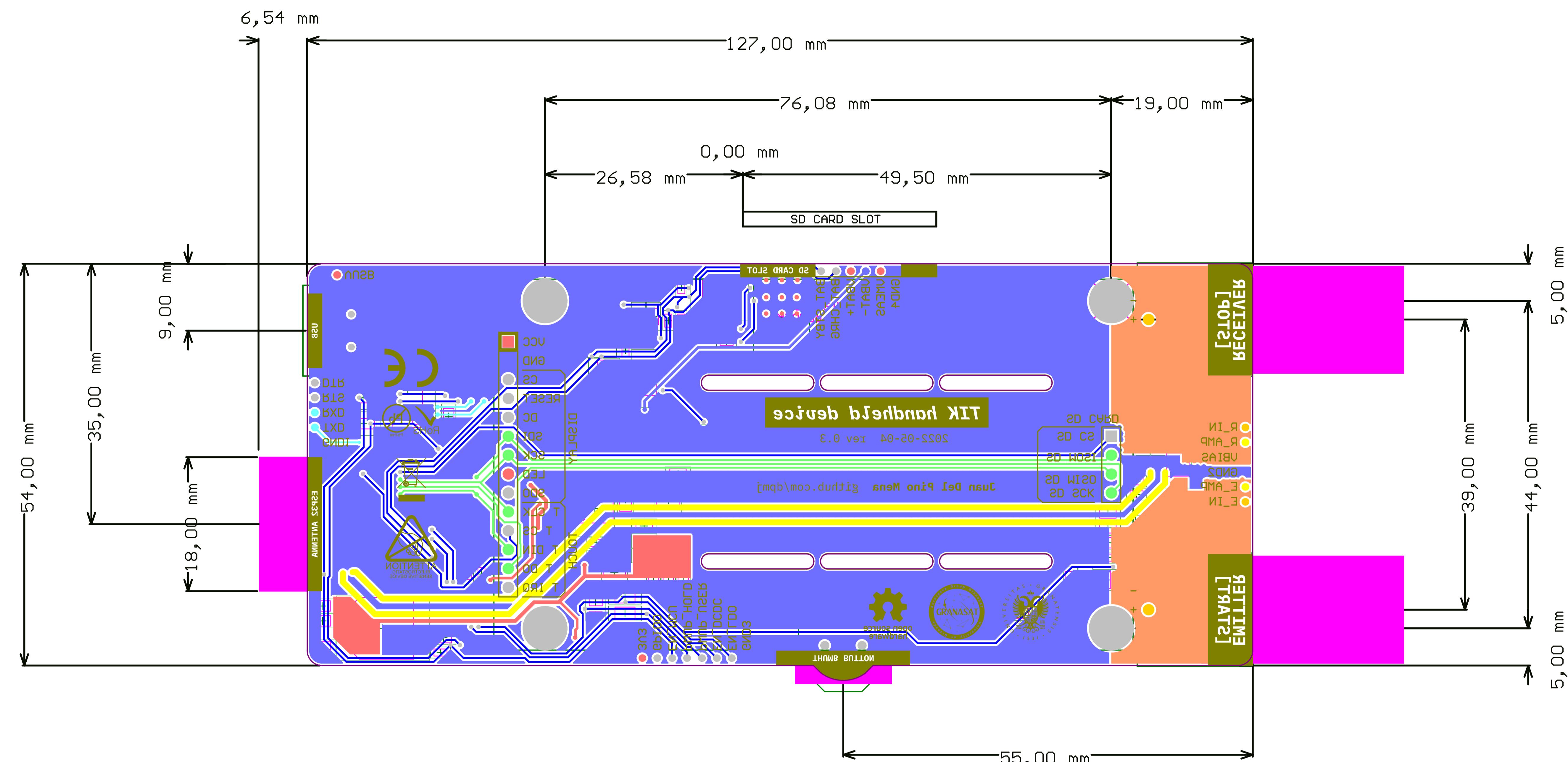
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Date: 2022-05-04
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A

**VISIBLE LAYERS:**

Board outline + Multilayer + Bottom
overlay + Bottom layer + Keep-out
+ dimensions

TIK handheld device PCB

PCB orientation: vertical. Screen facing front, BNCs on top, USB at the bottom, SD Card reader at the left, powerup button at the bottom front right, and multipurpose button on the right side.

Designer's signature:

Sheet title: TIK Handheld Device PCB

Project title: TIK_HandheldDevice

Supervisor's signature:

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